Product Change Notification - RMES-09VPXZ131

Date:

24 Aug 2019

Product Category:

Others; Ethernet PHYs

Affected CPNs:

Notification subject:

CCB 2922 Final Notice: Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Pre Change:

Assembled at TICP using gold (Au) bond wire and CEL9200 molding compound material.

Post Change:

Assembled at ASE using gold (Au) bond wire and G631H molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Taiwan IC Packing Corp (TICP)	ASE Inc. (ASE)
Lead frame material	C7025	C7025
Wire material	Au	Au
Die attach material	EN4900	CRM-1076WA
Mold compound material	CEL9200	G631H

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying ASE as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 08, 2018 (date code:1810)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	April 2017				->	February 2018				March 2018				
Workweek	14	15	16	17		05	06	07	08	09	10	11	12	13
Initial PCN Issue Date				X										
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date											X			

Qualification Report:Method to Identify Change:
Traceability code
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.
Revision History:
April 28, 2017: Issued initial notification.
May 8, 2017: Re-issued the initial notification to notify all affected customers.
February 08, 2018: Issued final notification. Attached the Qualification Report. Revised the affected parts list. Provided estimated first ship date on March 08, 2018.
April 20, 2018: Re-issued final PCN to update the Qualification Report.
August 24, 2019: Re-issued final PCN to revise affected CPN list to include parts that are only assembled in TICP.
The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):
PCN_RMES-09VPXZ131_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.
If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.